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## AMENDMENTS TO THE SPECIFICATION

- Please amend the Title, which begins on page 1, line 1, as follows:

HEAT SPREADER INTERCONNECT METHODOLOGY FOR THERMALLY  
ENHANCED PBGA PACKAGES

- Please amend the Cross-Reference to Related Application(s) section, which begins on page 1, line 3, as follows:

### CROSS-REFERENCE TO RELATED APPLICATION(S)

This is a divisional of co-pending application serial number 10/119,920, filed April 10, 2002, which is hereby incorporated by reference herein.

- Please replace the paragraph, which begins on page 6, line 13, with the following paragraph:

Specifically highlighted in the cross section of FIG. 1 are the heat spreader standoff features 38 of the heat spreader, which form the surfaces and method of interfacing the heat spreader 14 with the substrate 12 of the PBGA package. Heat spreader 14 may comprise metal ~~or~~ or may comprise thermally conductive epoxy.

- Please replace the paragraph, which begins on page 10, line 13, with the following paragraph:

In the cross sections that are shown in FIGS. 4a and 4b, the stand off 62 of the heat spreader 14 is inserted or aligned in the pre-attached solder ball ~~64-66~~ or by the use of solder paste (not shown). The flux-free solder ball 66 or solder paste is attached after wire bonding. The copper ground pad 64 is connected to the heat spreader 14 by soldering or by reflow

- Please amend the Abstract which begins on page 14, line 1, as follows which begins on the next page: